5-104071-1 - ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 5-104071-1 PCB Mount Header, Vertical, Board-to-Board, 10 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 10

Number of Rows: 1

Features



Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
	Vertical
Number of Positions	10
Number of Positions	10
Number of Positions Number of Rows	10 1
Number of Positions Number of Rows Board-to-Board Configuration	10 1

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Operating Voltage	30 VAC
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Termination Post & Tail Length2.54 mm[.1 in]Termination Method to PCBThrough Hole - SolderMechanical AttachmentVithMating RetentionWithMating Retention TypeLatchingaMating AlignmentWithMating Alignment TypePolarization
Mechanical Attachment Mating Retention With Mating Retention Type Latching Mating Alignment With
Mating RetentionWithMating Retention TypeLatchingMating AlignmentWith
Mating Retention Type Latching Mating Alignment With
Mating Alignment With
Mating Alignment Type Polarization
PCB Mount Retention Without
PCB Mount Alignment Without
Connector Mounting Type Board Mount
Housing Features
Centerline (Pitch) 1.27 mm[.05 in]
Housing Material Thermoplastic
Dimensions

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PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature (Max)	105 °C[221 °F]
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
UL Rating	Recognized
Compatible With Agency/Standards Products	CSA, UL
Compatible With Approved Standards Products	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	28
Packaging Method	Box, Tube

Other

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series AMPMODU System 50



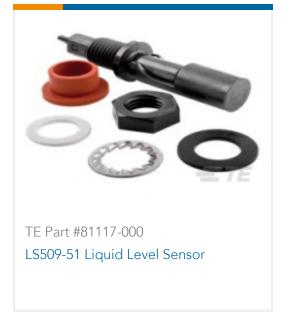
Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 10 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50







Documents

Product Drawings 10 SYSTEM 50 HDR SRST SHRD SN

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_5-104071-1_T.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-104071-1_T.3d_igs.zip

English

Customer View Model

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ENG_CVM_CVM_5-104071-1_T.3d_stp.zip
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English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Product Specifications
Application Specification

English